

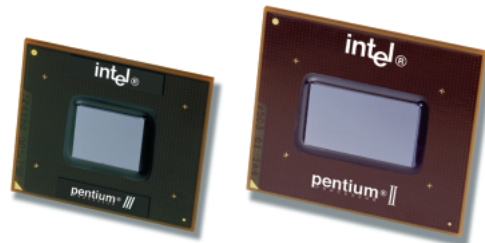
# Intel® Pentium® III and Pentium II Processors – Low Power for Applied Computing

## Pentium® III Processor—Low Power

The Pentium III processor—Low Power is bringing higher performance to applied computing. Available at 400 and 500 MHz with 256K L2 cache on die, it incorporates state-of-the-art technologies, like Intel's 0.18 micron manufacturing process, Dual Independent Bus (DIB) architecture, a front side bus speed of 100 MHz and Advanced Transfer Cache. These features make it ideal for performance-hungry embedded applications in areas like data communications, telecommunications, industrial automation and transaction terminals.

### This latest addition to the Intel Architecture features:

- Intel® Pentium® III processor—Low Power 400 and 500 MHz with 256K L2 cache on die with front side bus speed of 100 MHz
- 100 MHz front side bus. Allowing for a faster transfer of data, yielding an increase in performance
- Dual Independent Bus (DIB) architecture, offering up to three times the bandwidth over single bus. It combines two independent system buses for simultaneous parallel access to data.
- Supported with the Intel 440BX AGPset
- Support for MMX™ technology and SSE™ instruction sets. Enabling a more visual experience for the end user, and allowing for new applications such as real-time video encoding and speech recognition.
- 256K of L2 cache on-die coupled with Advanced Transfer Cache, improves processor performance
- Dynamic Execution: Three innovative data-processing techniques to manipulate data more intelligently and efficiently. These techniques predict and analyze software instructions to optimize processor workload.
- Built with Intel's 0.18 micron manufacturing process
- A compact BGA form factor (31 X 27 X 2.5mm) resulting in a small space requirement while yielding a high level of performance



### PENTIUM® III PROCESSORS - LOW POWER

PRODUCT NUMBER	CORE SPEED (MHz)	EXTERNAL BUS SPEED (MHz)	L2 CACHE	THERMAL DESIGN POWER (MAX)	VOLTAGE	T <sub>CASE</sub>	PACKAGE
KC80526NY400256	400	100	256K	10.1 watts	1.35V	0-100C	495 BGA
KC80526LY500256	500	100	256K	12.2 watts	1.35V	0-100C	495 BGA

## Intel® Pentium® II Processor—Low Power

- Intel Pentium II processor—Low Power with 256K L2 cache on die with front side bus speed of 66 MHz
- Available in processor speeds of:
  - 266 MHz
  - 333 MHz

### Intel's Pentium II processor—Low Power offers the following features:

- 66 MHz front side bus
- Dual Independent Bus (DIB) architecture, offering up to three times the bandwidth over single bus. It combines two independent system buses for simultaneous parallel access to data.
- Support for MMX™ technology instruction set. Ideal for graphics and multimedia intensive applications
- Supported with the Intel 440BX AGPset
- 256K of L2 cache on die
- Dynamic Execution: Three innovative data-processing techniques to manipulate data more intelligently and efficiently. These techniques predict and analyze software instructions to optimize processor workload
- Built with Intel's 0.25 micron manufacturing process
- A compact form factor (31 X 34 X 2.4 mm)

### PENTIUM® II PROCESSORS - LOW POWER

PRODUCT NUMBER	CORE SPEED (MHz)	EXTERNAL BUS SPEED (MHz)	L2 CACHE	THERMAL DESIGN POWER (MAX)	VOLTAGE	T <sub>CASE</sub>	PACKAGE
KC80524KX266256	266	66	256K	9.8 watts	1.6V	0-100C	615 BGA
KC80524KX333256	333	66	256K	11.8 watts	1.6V	0-100C	615 BGA

## Intel Access

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